

1. A semiconductor device with a plurality of semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;

a plurality of bonding pads, for connecting a bonding wire, provided on said wiring layer, thereto.

3. A semiconductor device according to claim 1, wherein said plurality of bonding pads are disposed so as to surround a semiconductor chip stacked on an upper surface of said wiring layer.

5. A semiconductor device with a plurality of semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;

25 a plurality of bonding pads, for connecting a bonding
wire, provided on said wiring layer, thereto and

6. A semiconductor device with a plurality of

a wiring layer disposed so as to be sandwiched between
said semiconductor chips,

a connection wiring for connecting among said bonding pads provided in said wiring layer, and

a via hole, connected to said bonding pad of a
10 semiconductor chip disposed below said wiring layer, and
provided on said wiring layer.